

WHAT IS CLAIMED IS:

1. A solid-state image device, comprising a package including at least one corner that has a recessed portion, wherein the recessed portion is defined by an end face including at least two linear portions observed when being seen from an upper surface side of the package.

2. A solid-state image device, comprising a package having at least two recessed portions formed at least at one selected from two adjacent side ends of the package, wherein the at least two recessed portions are defined by an end face including linear portions observed when being seen from an upper surface side of the package.

3. The solid-state image device according to claim 2, wherein the linear portions are substantially parallel to either of two adjacent side ends, respectively.

4. The solid-state image device according to claim 1, wherein the package comprises:
a member for patterning, on a surface of which a conductor pattern for transmitting signals from a solid-state image element is formed; and
a frame member that has an opening surrounding the solid-state image element and is positioned above the member for patterning, and
the at least two linear portions, in the recessed portion, observed when the recessed portion is seen from the upper surface side of the package, being formed of the member for patterning.

5. The solid-state image device according to claim 2, wherein the package comprises:
a member for patterning, on a surface of which a conductor pattern for transmitting signals from a solid-state image element is formed; and
a frame member that has an opening surrounding the solid-state image element and is positioned above the member for patterning, and
the linear portions, in the at least two recessed portions, observed when the at least two recessed portions are seen from the upper surface side of the package, being formed of the member for patterning.

6. A method of manufacturing a solid-state image device, comprising:
forming at least two through holes in a ceramic green sheet;
baking the ceramic green sheet to obtain a ceramic baked product;
and

5 dividing the ceramic baked product to obtain a package so that at
least two recessed portions are formed from the at least two through holes in
the package,

wherein the at least two through holes are positioned so that the at
least two recessed portions are formed at least at one selected from two
10 adjacent side ends of the package, and

the at least two through holes are formed to have shapes
surrounded by end faces including linear portions observed when being seen
from an upper surface side of the package to form linear portions on end
faces defining the at least two recessed portions.

15 7. A method of manufacturing a solid-state image device, comprising:
preparing at least two ceramic green sheets and forming, in the at
least two ceramic green sheets, through holes with substantially rectangular
shapes on virtual parting lines arranged in a reticulated form observed when
20 being seen from upper surface sides of the at least two ceramic green sheets,
with vertices of the substantially rectangular shapes not positioned on the
virtual parting lines;

laminating the at least two ceramic green sheets with the virtual
parting lines coinciding substantially in their lamination direction to form a
25 laminate;

baking the laminate to obtain a ceramic baked product;

dividing the ceramic baked product along the virtual parting lines to
obtain a plurality of packages having recessed portions formed from the
through holes.

30 8. A method of manufacturing a solid-state image device, wherein a
package with first and second end faces formed by removing a portion at
least at one selected from two adjacent side ends of the package is positioned,
using a positioning jig provided with first and second projections coming into
35 contact with the first and second end faces along their shapes respectively,
with the first and second projections being brought into contact with the first
and second end faces along their shapes respectively, and in this state, a

solid-state image element is fixed to the package.

9. The method of manufacturing a solid-state image device according to claim 8, wherein when the package is seen from its upper surface side, contact faces between the first and second end faces and the first and second projections are formed substantially in at least one selected from a linear shape and an arc shape.

10. A camera comprising;
a solid-state image device according to claim 1; and
a lens block having at least two projections coming into contact with the at least two linear portions respectively, which are observed when the solid-state image device is seen from the upper surface side, in the recessed portion along their shapes and a lens focusing external light onto a solid-state image element included in the solid-state image device,
wherein the solid-state image device and the lens block are positioned with the at least two projections being in contact with the at least two linear portions along their shapes, respectively.

11. A camera comprising;
a solid-state image device according to claim 2; and
a lens block having at least two projections coming into contact with the linear portions respectively, which are observed when the solid-state image device is seen from the upper surface side, in the at least two recessed portion along their shapes and a lens focusing external light onto a solid-state image element included in the solid-state image device,
wherein the solid-state image device and the lens block are positioned with the at least two projections being in contact with the linear portions along their shapes, respectively.